

## Electronic Patent Application Fee Transmittal

Application Number:	10538306			
Filing Date:	09-Jun-2005			
Title of Invention:	Copper alloy for wiring, semiconductor device, method for forming wiring and method for manufacturing semiconductor device			
First Named Inventor/Applicant Name:	Makoto Ueki			
Filer:	Bruce Elliot Kramer/derrick hill			
Attorney Docket Number:	Q88465			

Filed as Large Entity

### **U.S. National Stage under 35 USC 371 Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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**Basic Filing:**

**Pages:**

**Claims:**

**Miscellaneous-Filing:**

**Petition:**

**Patent-Appeals-and-Interference:**

**Post-Allowance-and-Post-Issuance:**

**Extension-of-Time:**

Extension - 1 month with \$0 paid	1251	1	130	130
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				<b>130</b>